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*Sub J*  
~~50. (Amended) A wireless communication device comprising:~~

~~a housing including an upper surface, a lower surface, and at least one side~~

~~intermediate the upper surface and the lower surface and having a dimension less than~~

~~smallest dimensions of the upper surface and the lower surface, and the at least one side~~

~~surface having visibly perceptible indicia thereon;~~

~~communication circuitry within the housing and the communication circuitry being~~

configured to communicate wireless signals; and

wherein the communication circuitry comprises radio frequency identification device circuitry.

51. The device according to claim 50 wherein the housing comprises an encapsulant which contacts the communication circuitry.

52. The device according to claim 50 wherein the at least one side surface has a dimension less than about 100 mils.

53. Cancel.

54. (Amended) A wireless communication device comprising:

a substrate having a support surface defined by a perimetral edge;

communication circuitry elevationally over the support surface of the substrate and

configured to communicate wireless signals; and

an encapsulant elevationally over the support surface and configured to encapsulate

at least portions of the support surface of the substrate and the communication circuitry,

and wherein the encapsulant and the substrate respectively define an upper surface and

a lower surface and have a thickness less than a smallest dimension of the perimetral

edge, and the encapsulant includes visibly perceptible indicia intermediate the upper

surface and the lower surface.

55. The device according to claim 54 wherein the support surface comprises a surface substantially in the shape of a rectangle.
56. The device according to claim 54 wherein the encapsulant contacts at least portions of the support surface and the communication circuitry.
57. The device according to claim 54 wherein the encapsulant and the substrate have a thickness less than about 100 mils.
58. The device according to claim 54 wherein the communication circuitry comprises radio frequency identification device circuitry.
59. A wireless communication device comprising:  
communication circuitry configured to communicate wireless signals; and  
an encapsulant configured to encapsulate and contact at least a portion of the communication circuitry, wherein the encapsulant defines at least one side surface and the at least one side surface has visibly perceptible information thereon.
60. (Amended) The device according to claim 59 wherein the at least one side surface of the encapsulant has a thickness less than about 100 mils.

*Object* [ 61. The device according to claim 59 wherein the communication circuitry comprises radio frequency identification device circuitry.

*10 J* [ 62. A radio frequency identification device comprising:  
a housing including an upper surface and a lower surface which define a housing thickness of less than about 100 mils intermediate the lower surface and the upper surface, and the housing has visibly perceptible indicia thereon intermediate the upper surface and the lower surface; and  
communication circuitry within the housing and configured to communicate wireless signals.

*PL* [ 63. The device according to claim 62 wherein the housing comprises an encapsulant which contacts at least portions of the support surface and the communication circuitry.

*PL* [ 64. The device according to claim 62 further comprising an antenna within the housing and coupled with the communication circuitry.

*PL* [ 65. A radio frequency identification device comprising:  
a substrate having a support surface;  
radio frequency identification device circuitry elevationally over the support surface and configured to communicate wireless signals;

a power source elevationally over the support surface and coupled with the radio frequency identification device circuitry;

an antenna elevationally over the support surface and coupled with the radio frequency identification device circuitry; and

an encapsulant contacting at least portions of the support surface, the radio frequency identification device circuitry, the power source and the antenna, wherein the encapsulant and the substrate form a housing having an upper surface and a lower surface interconnected by at least one side surface, and the at least one side surface has a dimension less than smallest dimensions of the upper and lower surfaces, and the at least one side surface includes visibly perceptible indicia.

66. (Amended) A method of forming a wireless communication device comprising:

providing communication circuitry configured to communicate wireless signals;

providing a housing including an upper surface, a lower surface and at least one side surface about the communication circuitry, the at least one side surface has a dimension less than smallest dimensions of the upper surface and the lower surface;

providing visibly perceptible indicia on the at least one side surface; and

wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

67. The method according to claim 66 wherein the providing the housing comprises encapsulating at least a portion of the communication circuitry with an encapsulant.

68. The method according to claim 67 wherein the encapsulating comprises contacting at least the encapsulated portion of the communication circuitry with the encapsulant.

69. The method according to claim 66 wherein the at least one side surface has a dimension less than about 100 mils.

70. Cancel.

71. A method of forming a wireless communication device comprising:  
providing a substrate having a support surface defined by at least one perimetral edge;

providing communication circuitry elevationally over the support surface of the substrate and configured to communicate wireless signals;

encapsulating at least portions of the support surface of the substrate and the communication circuitry using an encapsulant, the encapsulant and the substrate respectively define an upper surface and a lower surface and have a thickness less than a smallest dimension of the at least one perimetral edge; and

providing visibly perceptible indicia on the encapsulant intermediate the upper surface and the lower surface.

72. The method according to claim 71 wherein the providing the substrate comprises providing the substrate having a substantially rectangular shape.

73. The method according to claim 71 wherein the encapsulating comprises contacting at least the encapsulated portions of the support surface of the substrate and the communication circuitry with the encapsulant.

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74. The method according to claim 71 wherein the encapsulant and the substrate have a thickness less than about 100 mils.

75. The method according to claim 71 wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

76. A method of forming a wireless communication device comprising:  
providing communication circuitry configured to communicate wireless signals;  
encapsulating at least a portion of the communication circuitry with an encapsulant which contacts at least the encapsulated portion of the communication circuitry, the encapsulant forming at least one side surface; and  
providing visibly perceptible indicia upon the at least one side surface of the encapsulant.

100 100  
77. The method according to claim 76 wherein the at least one side surface of the encapsulant has a dimension less than about 100 mils.

100 100  
78. The method according to claim 76 wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

100 100  
79. A method of forming a radio frequency identification device comprising:

100 100  
providing radio frequency identification device circuitry configured to communicate wireless signals;

100 100  
providing a housing including an upper surface, a lower surface, and at least one side surface about the communication circuitry, the at least one side surface having a dimension less than about 100 mils; and

100 100  
providing visibly perceptible indicia on the at least one side surface.

100 100  
80. The method according to claim 79 wherein the providing the housing comprises providing an encapsulant over at least a portion of a support surface of a substrate.

100 100  
81. The method according to claim 80 wherein the encapsulant contacts at least portions of the support surface and the radio frequency identification device circuitry.

82. A method of forming a radio frequency identification device comprising:  
providing radio frequency identification device circuitry configured to communicate  
wireless signals;  
coupling a power source with the radio frequency identification device circuitry;  
coupling an antenna with the radio frequency identification device circuitry;  
providing a housing including an upper surface, a lower surface and at least one  
side surface about at least portions of the radio frequency identification device circuitry, the  
power source and the antenna, the at least one side surface having a dimension less than  
smallest dimensions of the upper surface and the lower surface; and  
providing visibly perceptible indicia on the at least one side surface.

66 71

83. The device according to claim 50 wherein the communication circuitry is  
configured to implement backscatter communications.

84. The device according to claim 50 further comprising a battery coupled with  
the communication circuitry.

85. The device according to claim 54 wherein the communication circuitry is  
configured to implement backscatter communications.

86. The device according to claim 54 further comprising a battery coupled with  
the communication circuitry.

87. The device according to claim 59 wherein the communication circuitry is configured to implement backscatter communications.
88. The device according to claim 59 further comprising a battery coupled with the communication circuitry.
89. The device according to claim 62 wherein the communication circuitry is configured to implement backscatter communications.
90. The device according to claim 62 further comprising a battery coupled with the communication circuitry.
91. The method according to claim 66 wherein the providing communication circuitry comprises providing backscatter communication circuitry.
92. The method according to claim 66 further comprising electrically coupling a battery with the communication circuitry.
93. The method according to claim 71 wherein the providing communication circuitry comprises providing backscatter communication circuitry.

94. The method according to claim 71 further comprising electrically coupling a battery with the communication circuitry.

95. The method according to claim 76 wherein the providing communication circuitry comprises providing backscatter communication circuitry.

96. The method according to claim 76 further comprising electrically coupling a battery with the communication circuitry.

97. The method according to claim 79 wherein the providing the radio frequency identification device circuitry comprises providing backscatter circuitry.

98. The method according to claim 79 further comprising electrically coupling a battery with the radio frequency identification device circuitry.

99. (New) A wireless communication device comprising:

a housing including an upper surface, a lower surface, and at least one side intermediate the upper surface and the lower surface and having a dimension less than smallest dimensions of the upper surface and the lower surface, and the at least one side surface having visibly perceptible indicia thereon; and

communication circuitry within the housing and the communication circuitry being configured to communicate wireless signals;

wherein the communication circuitry is configured to implement backscatter communications.

100. (New) A method of forming a wireless communication device comprising:  
providing communication circuitry configured to communicate wireless signals;  
providing a housing including an upper surface, a lower surface and at least one side surface about the communication circuitry, the at least one side surface has a dimension less than smallest dimensions of the upper surface and the lower surface; and  
 providing visibly perceptible indicia on the at least one side surface;  
wherein the providing communication circuitry comprises providing backscatter communication circuitry.

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